

AMENDMENTS TO THE SPECIFICATION

IN THE DRAWING FIGURES:

Kindly replace FIG. 2 of the subject application with the revised FIG. 2 attached hereto.

FIG. 2 has been revised to improve legibility of the figure. No new matter is added by the revision to FIG. 2.

IN THE WRITTEN DESCRIPTION:

Kindly replace paragraph [0009] with the following amended paragraph:

To provide the above and other features of an embodiment of the present invention, a method for depositing a dielectric layer having a multi-layer structure on a substrate includes forming an oxidation barrier layer on a surface of a substrate; forming a plurality of dielectric layers on the oxidation barrier layer, wherein one of a plurality of additional oxidation barrier layers is disposed between each of the plurality of dielectric layers and an adjacent dielectric layer.

Changes in the previous paragraph are indicated by strikethrough for deletions and underlining for insertions.

To provide the above and other features of an embodiment of the present invention, a method for depositing a dielectric layer having a multi-layer structure on a substrate includes forming an ~~a~~ first oxidation barrier layer on a surface of a substrate; ~~forming a first dielectric layer on the first oxidation barrier layer; forming a second oxidation barrier layer on the first dielectric layer;~~ forming a plurality of additional dielectric layers on the ~~second~~ oxidation barrier layer, wherein one of a plurality of additional oxidation barrier layers is disposed between each of the plurality of additional dielectric layers ~~has one of a plurality of additional oxidation barrier layers disposed between itself and an adjacent additional dielectric layer.~~